

## DESCRIPTION

The MXD3016M uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It can be used in a wide variety of applications.

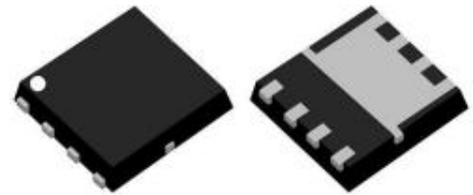
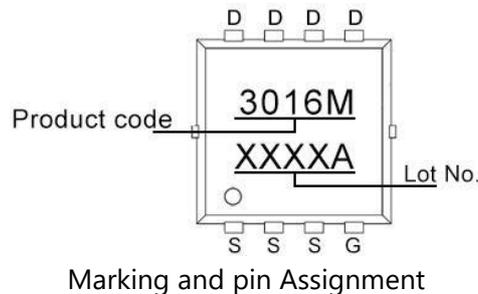
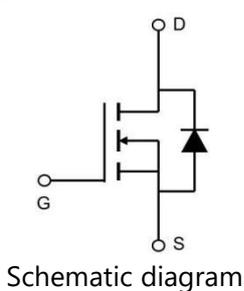
## GENERAL FEATURES

- $V_{DS}=30V$ ,  $I_D=45A$   
 $R_{DS(ON)}(Typ.)=4.7m\Omega$  @  $V_{GS}=10V$   
 $R_{DS(ON)}(Typ.)=6.5m\Omega$  @  $V_{GS}=4.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

## APPLICATION

- PWM applications
- DC/DC Converters
- UPS

## PINOUT



## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN3016M	-55°C to 150°C	PDFN3.3X3.3-8L	-

## ABSOLUTE MAXIMUM RATINGS ( $T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	45	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	110	A
Maximum Power Dissipation	$P_D$	29.8	W
Avalanche Current	$I_{AS}$	26	A
Avalanche Energy(L=0.5mH)	$E_{AS}$	169	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

## THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case <sup>(Note2)</sup>	$R_{\theta JC}$	4.2	°C/W
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.



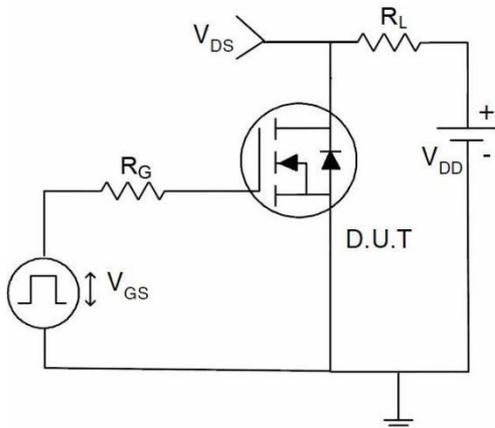
**ELECTRICAL CHARACTERISTICS** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note2)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.65	2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$	-	4.7	6.5	m $\Omega$
		$V_{GS}=4.5V, I_D=12A$	-	6.5	10	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=10V, I_D=11A$	-	24	-	S
<b>Dynamic Characteristics</b> <sup>(Note3)</sup>						
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, F=1.0MHz$	-	2000	-	pF
Output Capacitance	$C_{oss}$		-	235	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	175	-	pF
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=15V, R_L=0.75\Omega, V_{GS}=10V, R_G=3\Omega$	-	8.8	-	nS
Turn-on Rise Time	$t_r$		-	12.2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	29.5	-	nS
Turn-Off Fall Time	$t_f$		-	8.6	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=15V, I_D=20A, V_{GS}=10V$	-	20.7	-	nC
Gate-Source Charge	$Q_{gs}$		-	3.5	-	nC
Gate-Drain Charge	$Q_{gd}$		-	5.1	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note2)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current <sup>(Note1)</sup>	$I_S$		-	-	16	A

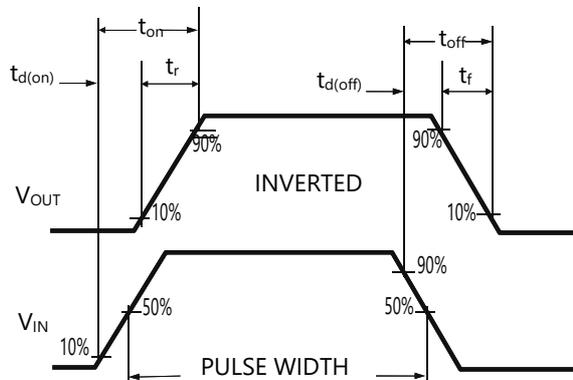
Note 1. Surface Mounted on FR4 Board,  $t \leq 10$  sec.  
 Note 2. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .  
 Note 3. Guaranteed by design, not subject to product.

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

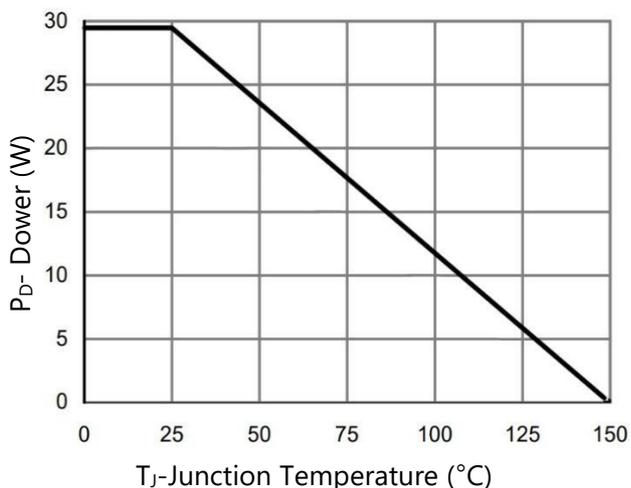
**Figure 1. Switching Test Circuit**



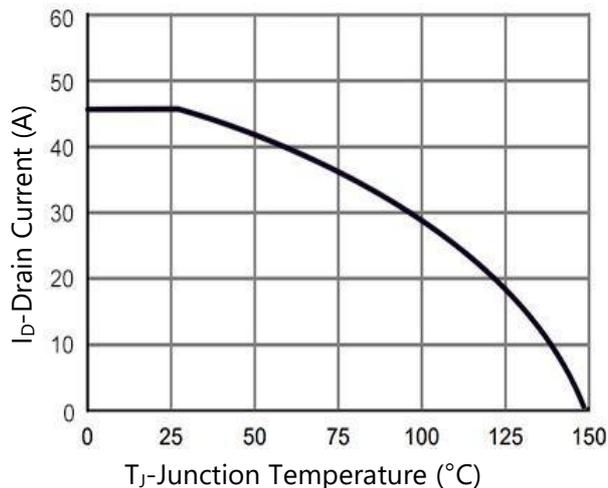
**Figure 2. Switching Waveform**



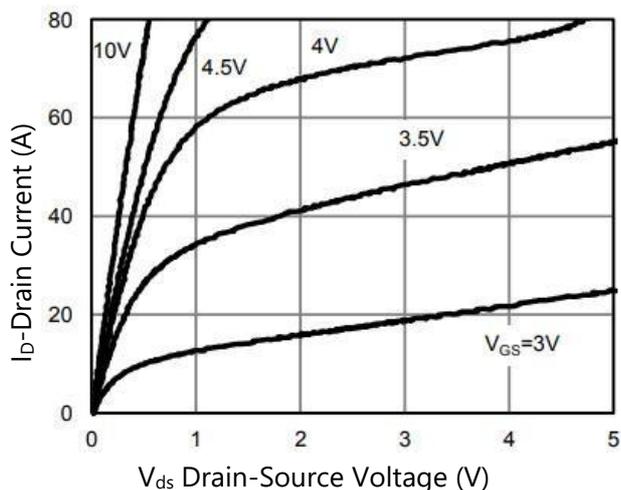
**Figure 3. Power Dissipation**



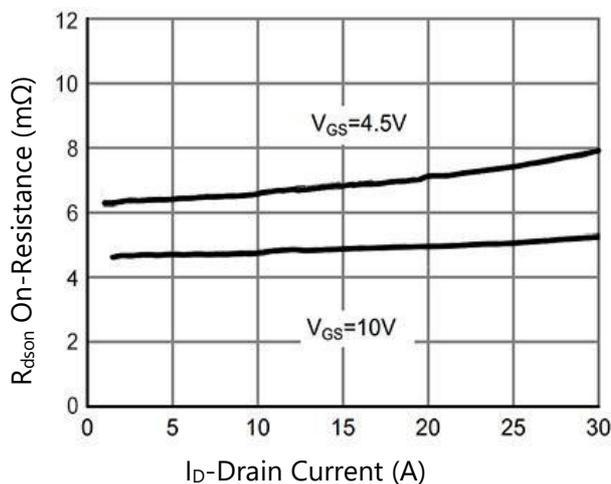
**Figure 4. Drain Current**



**Figure 5. Output Characteristics**



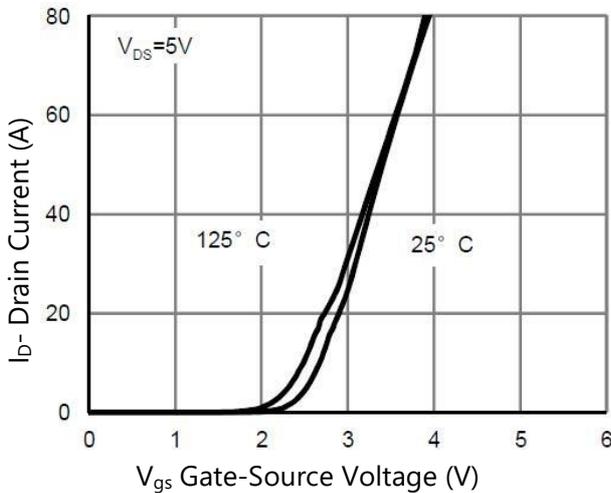
**Figure 6. R<sub>dson</sub> vs Drain Current**



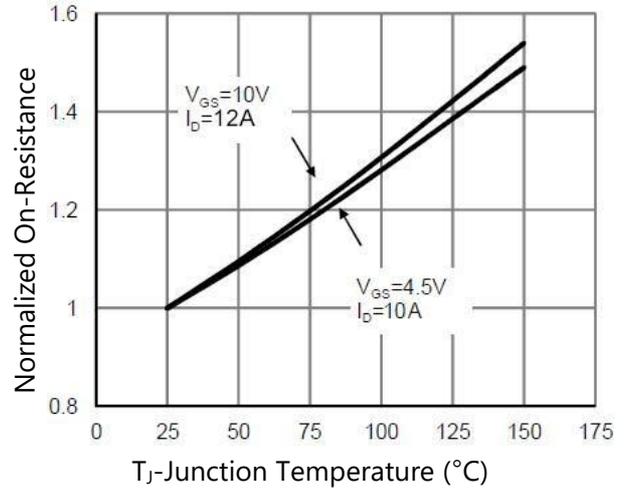


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

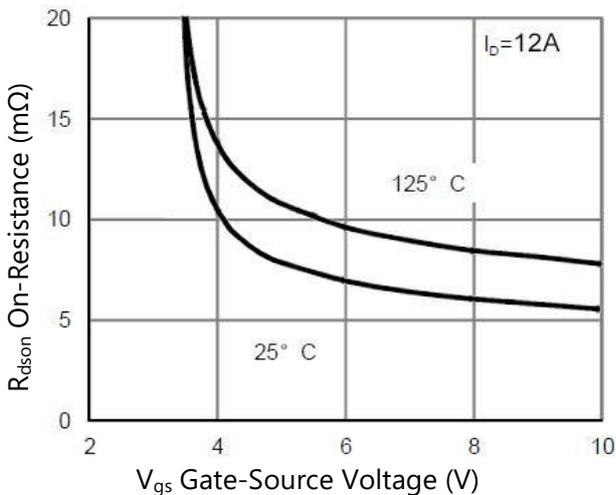
**Figure 7. Transfer Characteristics**



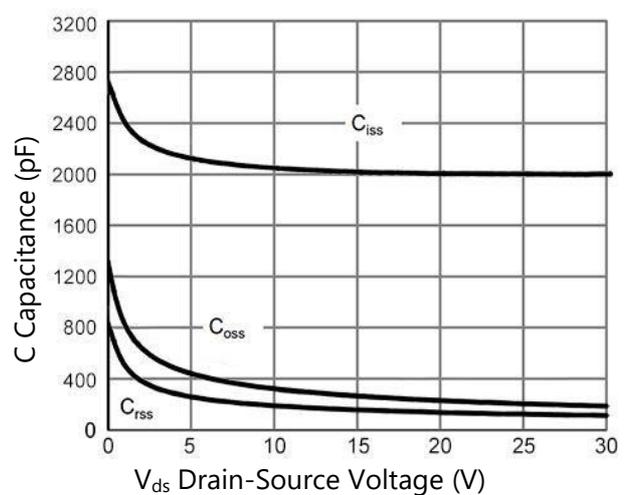
**Figure 8.  $R_{dson}$  vs Junction Temperature**



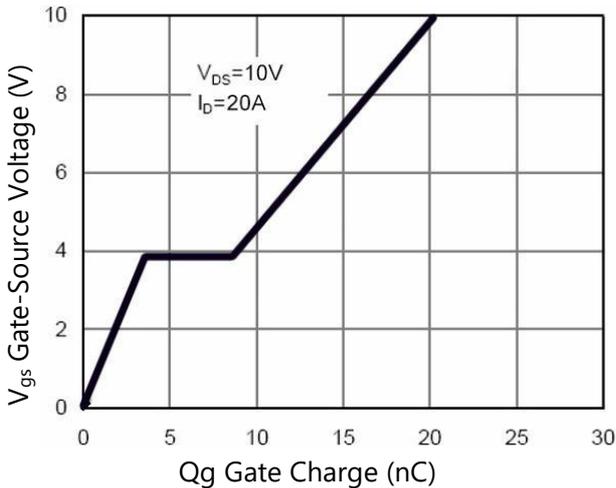
**Figure 9.  $R_{dson}$  vs  $V_{gs}$**



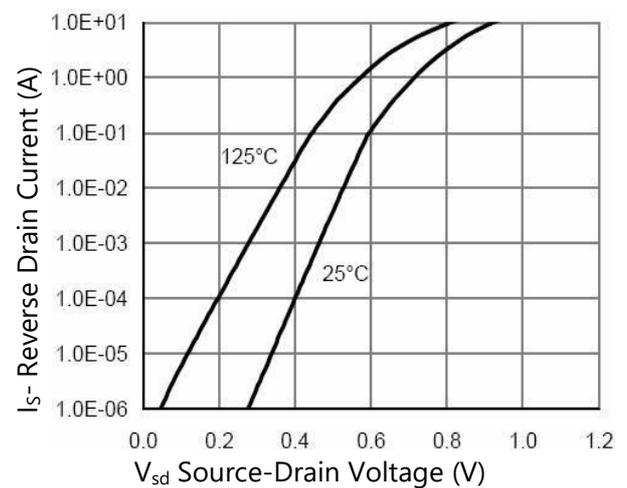
**Figure 10. Capacitance vs  $V_{DS}$**



**Figure 11. Gate Charge**

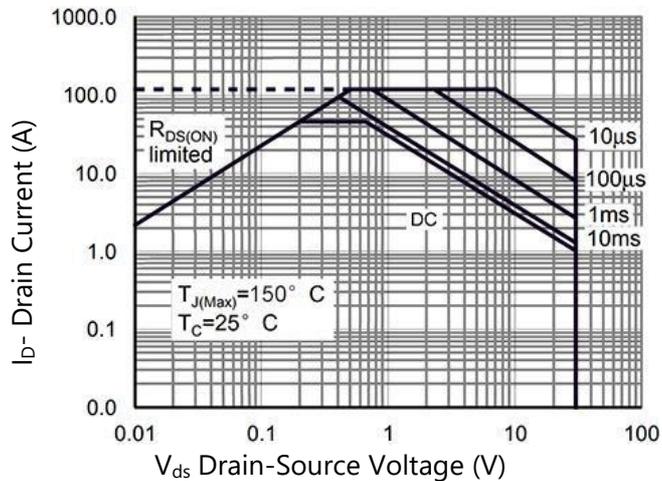


**Figure 12. Source- Drain Diode Forward**

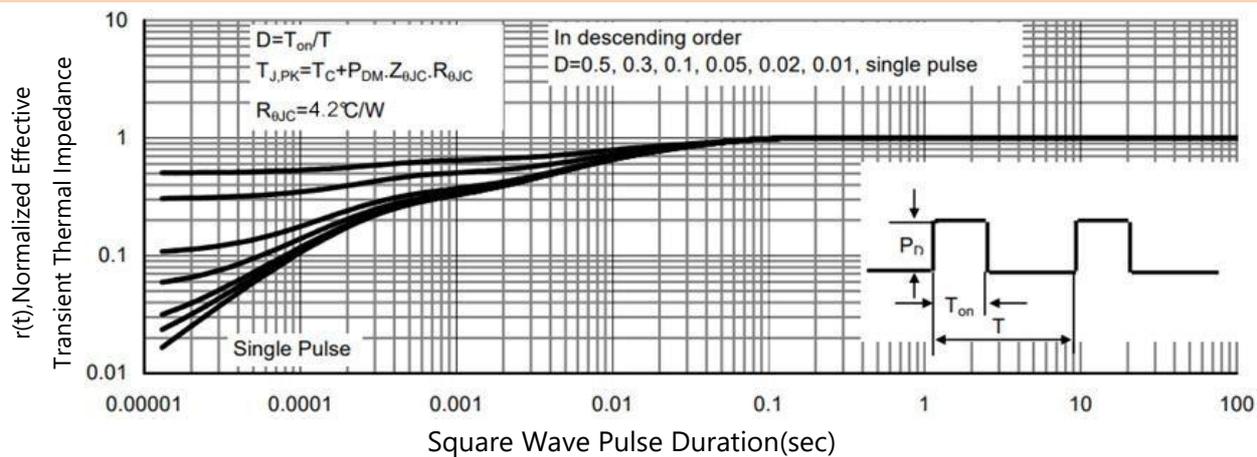


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 13. Safe Operation Area**

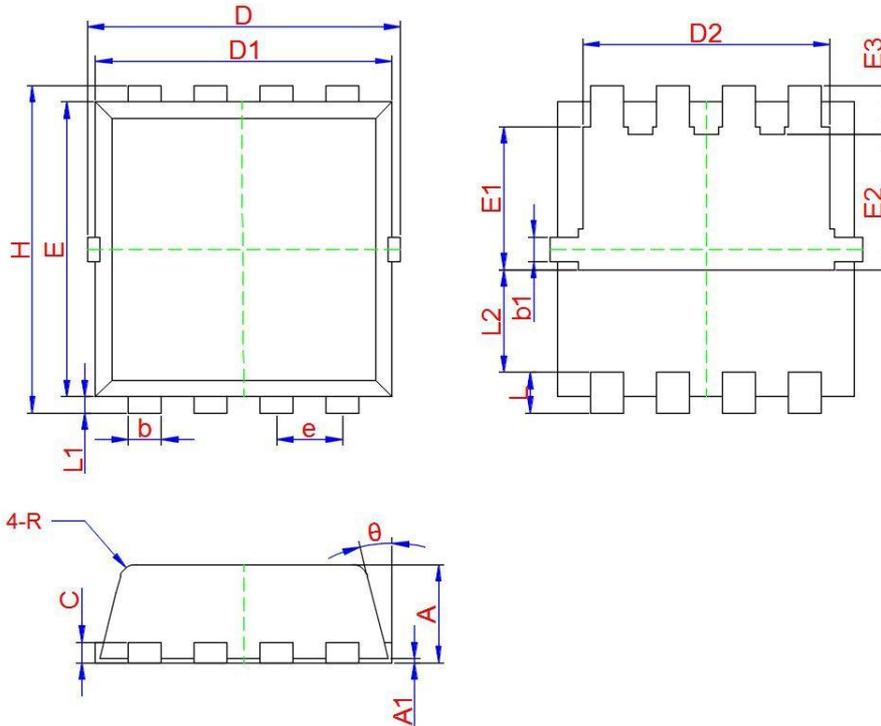


**Figure 14. Normalized Maximum Transient Thermal Impedance**



**PACKAGE INFORMATION**

PDFN3.3X3.3-8L



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.700	0.800	0.900
A1	0.000	0.030	0.050
b	0.240	0.300	0.350
b1	0.080	0.130	0.180
c	0.152 TYP.		
D	3.250	3.320	3.400
D1	3.050	3.150	3.250
D2	2.400	2.500	2.600
E	3.000	3.100	3.200
E1	1.350	1.450	1.550
E2	1.200	1.300	1.400
E3	0.400	0.500	0.600
e	0.650 TYP.		
H	3.200	3.300	3.400
L	0.300	0.400	0.500
L1	0.100	0.150	0.200
L2	1.130 TYP.		
R	0.200 TYP.		
theta	6°	10°	14°